

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicants: Hoffman, Paul; Mathews, Doug  
Assignee: Amkor Technology, Inc.  
Title: Shielded Semiconductor Package With Single Sided Substrate And Method For Making The Same  
Serial No.: 09/848,932 Filing Date: May 4, 2001  
Examiner: Cruz, Lourdes C. Group Art Unit: 2827  
Docket No.: M-9954 US

San Francisco, California  
July 27, 2002

BOX NON-FEE AMENDMENT  
COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

Applicants respond to the Office Action dated June 21, 2002 as follows. Applicants elect Group I, i.e., claims 11-21. Applicants are canceling claims 1-10 and are adding new claims 22-31.

IN THE CLAIMS

Please cancel claims 1-10 and add new claims 22-31. Claim 20 has been amended to correct a minor typographical error. The following is a clean version of the entire set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides marked up version of claim 20 containing the newly introduced changes.

Claims 1-10 are cancelled.

11. A semiconductor chip package comprising:  
a substrate;  
a metallization layer formed on one side of the substrate;